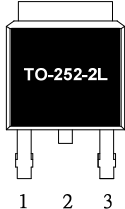
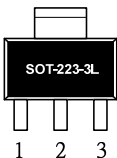
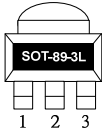
	<b>P<sub>D</sub> : Power Dissipation</b>
	<b>T<sub>J</sub> : Junction Temp. (Max +125°C)</b>
	<b>T<sub>A</sub> : Ambient Temp. (環境溫度一般以室溫 25°C 計算)</b>
	<b>T<sub>C</sub> : Case Temp. (IC 表面量測溫度)</b>
	<b>θ<sub>JA</sub> : Junction to Ambient Thermal Resistance</b>
	<b>θ<sub>JC</sub> : Junction to Case Thermal Resistance</b>
<b>IC Thermal Path</b>	

The power dissipation is defined as

$$P_D = I_{OUT} \times (V_{IN} - V_{OUT})$$

The maximum power dissipation depends on the thermal resistance of IC package, PCB layout, the rate of surrounding airflow and temperature difference between junction and ambient. The maximum power dissipation can be calculated by the following formula :

$$P_{D(MAX)} = \frac{(T_J - T_A)}{\theta_{JA}}$$

Package			
PD <sub>(MAX)</sub>	1.5 W	0.9 W	0.5 W

$$P_D = (V_{in} - V_{out}) \times I_{out} < P_{D(MAX)}$$

And the case temperature, T<sub>C</sub>, can be calculated as follows :

$$T_J = T_C + (P_D \times \theta_{JC})$$

For this operating condition, T<sub>J</sub> is lower than the absolute maximum operating junction Temperature (≤ 125 °C).